IN THE UNITED STATES
PATENT AND TRADEMARK OFFICE

PATENT APPLICATION

Applicants: **Dor et al.**

Case: **4744 FET/MDR**

Serial No.: **09/905,313** Filed: **July 13, 2001**

Group Art Unit: **2184**

Examiner: **Not yet assigned**

Title: **METHOD AND APPARATUS FOR COMMUNICATING IMAGES, DATA, OR OTHER INFORMATION IN A DEFECT SOURCE IDENTIFIER**

Assistant Commissioner for Patents
Washington, D. C. 20231

S I R:

PRELIMINARY AMENDMENT

Please amend the above-identified patent application as follows:

IN THE SPECIFICATION

Please replace existing paragraphs [001] and [016] with the following paragraphs:

[001] This application claims benefit of United States provisional patent applications serial number 60/240,631, filed October 16, 2000, and 60/237,297, filed October 2, 2000 which are herein incorporated by reference. This application contains subject matter that is related to the subject matter described in US patent application serial numbers 09/905,514, 09/905,609 and 09/905,607, filed simultaneously herewith on July 13, 2001, which are each incorporated herein by reference in their entireties.

[016] One embodiment of a defect source identifier 100 is shown in FIG. 1 that identifies defect sources in the wafers processed by a wafer processing system 102.

One co-pending application that discloses one embodiment of the defect source identifier 100 is shown in U.S. Patent Application serial number 09/905,607, filed July 13, 2001, which is incorporated herein by reference. The defect source identifier 100 comprises a defect source identifier server 106, a network 110, and a plurality of defect source identifier clients 104. Each defect source identifier client 104 is coupled to a wafer processing system 102. The present disclosure describes a method and apparatus for communicating images, data, and/or other information between the different networked portions within the defect source identifier 100. The wafer processing system 102 includes one or more process cells 103. Each one of the process cells is configured to perform such processes on wafers as chemical vapor deposition (CVD), physical vapor deposition (PVD), electro-chemical plating (ECP), electroless deposition, other known deposition processes, or other known etching processes.

REMARKS

The above amendments have been made to add the appropriate serial numbers to the specification.

If the Examiner believes that there are any unresolved issues, it is requested that the Examiner telephone Raymond R. Moser Jr. at (732) 530-9404 so that appropriate arrangements can be made for resolving such issues as expeditiously as possible.

Respectfully submitted,

10-16-01

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CERTIFICATE OF MAILING under 37 C.F.R. 1.8(a)

I hereby certify that this correspondence is being deposited on Oct. 17, 2001 with the United States Postal Service as first class mail, with sufficient postage, in an envelope addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231.

Khaled Shirazi
Signature

10-17-01
Date of signature

APPENDIX
MARK-UP OF AMENDED SPECIFICATION

[001] This application claims benefit of United States provisional patent applications serial number 60/240,631, filed October 16, 2000, and 60/237,297, filed [10/2/00] October 2, 2000 which are herein incorporated by reference. This application contains subject matter that is related to the subject matter described in US patent application serial numbers 09/905,514, 09/905,609 and 09/905,607 [_____, _____, and _____, (Attorney dockets 4745FET/MDR, 4747FET/MDR, and 4748FET/MDR)], filed simultaneously herewith on July 13, 2001, which are each incorporated herein by reference in their entireties.

[016] One embodiment of a defect source identifier 100 is shown in FIG. 1 that identifies defect sources in the wafers processed by a wafer processing system 102. One co-pending application that discloses one embodiment of the defect source identifier 100 is shown in U.S. Patent Application serial number 09/905,607, filed July 13, 2001 [S/N_____, filed____ (Attorney Docket 4748 FET/MDR)], which is incorporated herein by reference. The defect source identifier 100 comprises a defect source identifier server 106, a network 110, and a plurality of defect source identifier clients 104. Each defect source identifier client 104 is coupled to a wafer processing system 102. The present disclosure describes a method and apparatus for communicating images, data, and/or other information between the different networked portions within the defect source identifier 100. The wafer processing system 102 includes one or more process cells 103. Each one of the process cells is configured to perform such processes on wafers as chemical vapor deposition (CVD), physical vapor deposition (PVD), electro-chemical plating (ECP), electroless deposition, other known deposition processes, or other known etching processes.